

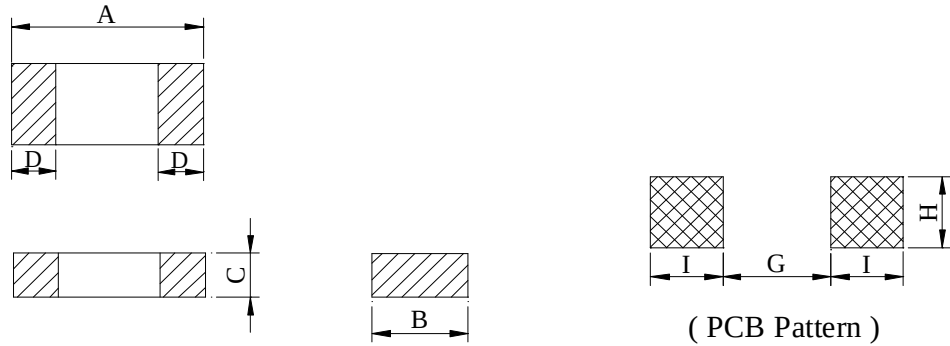
SPECIFICATION FOR APPROVAL

REF :

PAGE: 1

PROD. NAME	MULTILAYER CHIP INDUCTOR	ABC'S DWG NO.	MS3261□□□□L□-□□□
		ABC'S ITEM NO.	

I . CONFIGURATION & DIMENSIONS :



Unit : m/m

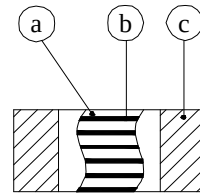
Series	A	B	C	D	G	H	I
MS3261	3.20±0.20	1.60±0.20	1.10±0.20	0.60±0.40	2.2	1.4	1.1

II . SCHEMATIC DIAGRAM :



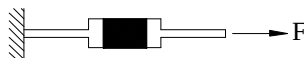
III . MATERIALS :

- a . Body : Ferrite
- b . Internal conductor : Silver or Ag / Pd
- c . Terminal : Cu/Sn
- d . Remark : Products comply with RoHS' requirements



IV . GENERAL SPECIFICATION :

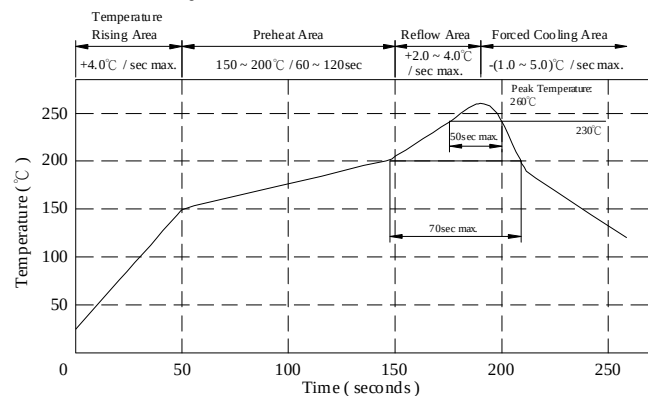
- a . Storage temp. : -40°C --- +105°C
- b . Operating temp. : -55°C --- +125°C
- c . Terminal storength :



Type	F (kgf)	time (sec)
MS3261	1.0	30±5

- d . Solderability : Preheat : 150±25°C for 60 seconds
Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent
Solder temp. : 260±5°C
Flux : Rosin
Dip time : 4±1 seconds

Peak Temp : 260°C max.
Max time above 230°C : 50sec max.
Max time above 200°C : 70sec max.



AR-001A


千如電子集團
 ABC ELECTRONICS GROUP.

SPECIFICATION FOR APPROVAL

REF :

PAGE: 2

PROD. NAME	MULTILAYER CHIP INDUCTOR	ABC'S DWG NO.	MS3261□□□□L□-□□□
		ABC'S ITEM NO.	

V . ELECTRICAL CHARACTERISTICS :

DWG No.	Inductance (μ H)	Q min	Test Freq. (MHz)	SRF (MHz) min.	RDC (Ω) max	IDC (mA) max
MS326147NML□ -□□□	0.047±20%	20	50	320	0.15	300
MS326168NML□ -□□□	0.068±20%	20	50	280	0.25	300
MS3261R10ML□ -□□□	0.100±20%	20	25	235	0.25	250
MS3261R12ML□ -□□□	0.120±20%	20	25	220	0.30	250
MS3261R15ML□ -□□□	0.150±20%	20	25	200	0.30	250
MS3261R18ML□ -□□□	0.180±20%	20	25	185	0.40	250
MS3261R22ML□ -□□□	0.220±20%	20	25	170	0.40	250
MS3261R27ML□ -□□□	0.270±20%	20	25	150	0.50	250
MS3261R33ML□ -□□□	0.330±20%	20	25	145	0.60	250
MS3261R39ML□ -□□□	0.390±20%	25	25	135	0.50	200
MS3261R47ML□ -□□□	0.470±20%	25	25	125	0.60	200
MS3261R56ML□ -□□□	0.560±20%	25	25	115	0.70	150
MS3261R68ML□ -□□□	0.680±20%	25	25	105	0.80	150
MS3261R82ML□ -□□□	0.820±20%	25	25	100	0.90	150
MS3261R0ML□ -□□□	1.000±20%	45	10	75	0.40	100
MS3261R2ML□ -□□□	1.200±20%	45	10	65	0.50	100
MS3261R5ML□ -□□□	1.500±20%	45	10	60	0.50	50
MS3261R8ML□ -□□□	1.800±20%	45	10	55	0.50	50
MS3261R2ML□ -□□□	2.200±20%	45	10	50	0.60	50
MS3261R7ML□ -□□□	2.700±20%	45	10	45	0.60	50
MS3261R3ML□ -□□□	3.300±20%	45	10	41	0.70	50
MS3261R9ML□ -□□□	3.900±20%	45	10	38	0.80	50
MS3261R7ML□ -□□□	4.700±20%	45	10	35	0.90	50
MS3261R6ML□ -□□□	5.600±20%	50	4	32	0.70	25
MS3261R8ML□ -□□□	6.800±20%	50	4	29	0.80	25
MS3261R2ML□ -□□□	8.200±20%	50	4	26	0.90	25
MS3261R0ML□ -□□□	10.000±20%	50	2	24	1.00	25

1). □ : Packaging Information.. ☐A : Bulk ☐B : Taping Reel

2)."-□□□":Reference code

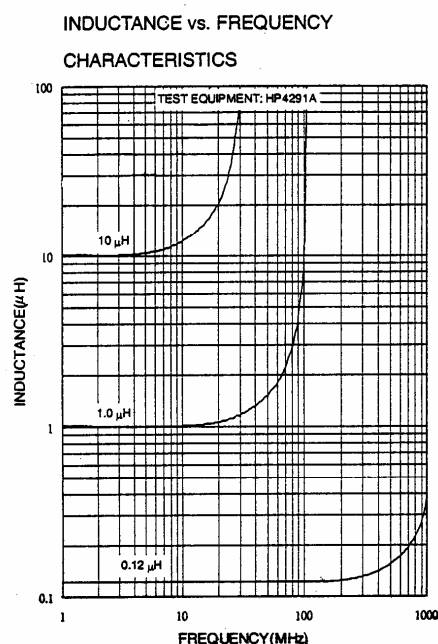
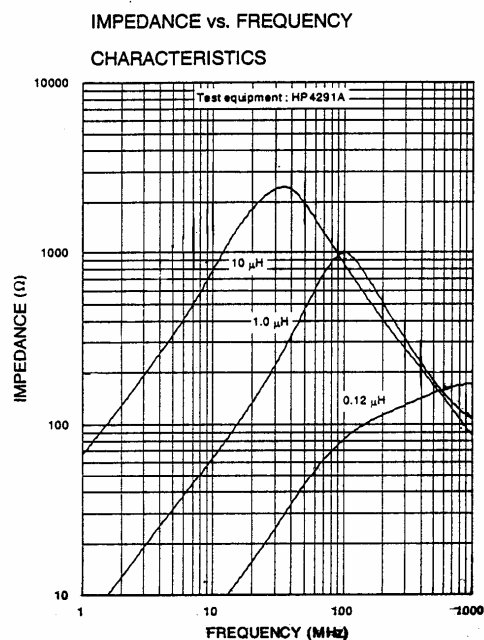
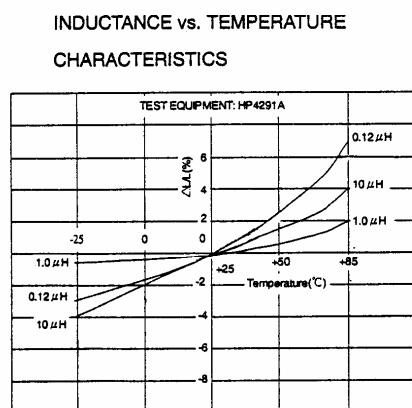
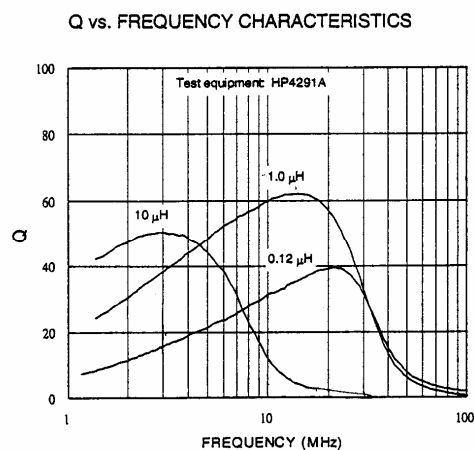
SPECIFICATION FOR APPROVAL

REF :

PAGE: 3

PROD. NAME	MULTILAYER CHIP INDUCTOR	ABC'S DWG NO.	MS3261□□□□L□-□□□
		ABC'S ITEM NO.	

VI . CURVE :



AR-001A

SPECIFICATION FOR APPROVAL

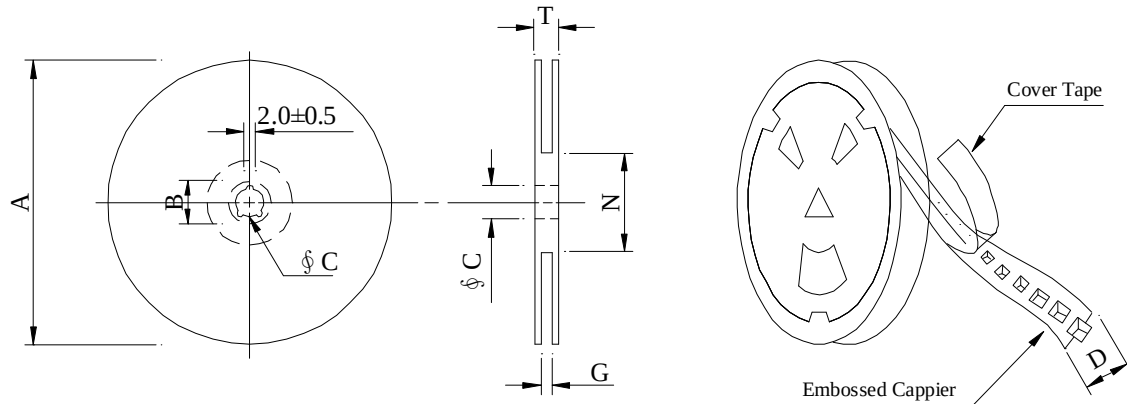
REF :

PAGE: 4

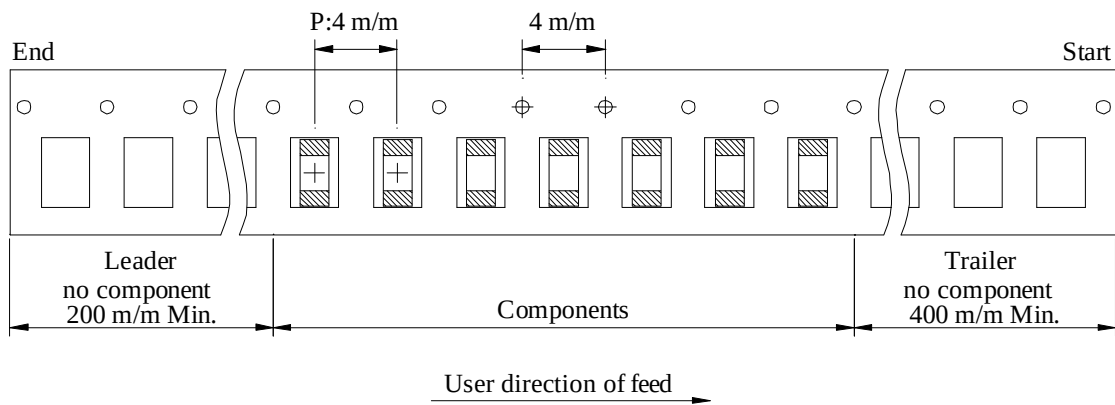
PROD. NAME	MULTILAYER CHIP INDUCTOR	ABC'S DWG NO.	MS3261□□□□L□-□□□
		ABC'S ITEM NO.	

VII . PACKAGING INFORMATION :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
MS3261	3,000	150	07 - 08	120,000	8.5	41 x 39 x 22

AR-001A



千如電子集團
ABC ELECTRONICS GROUP.

SPECIFICATION FOR APPROVAL

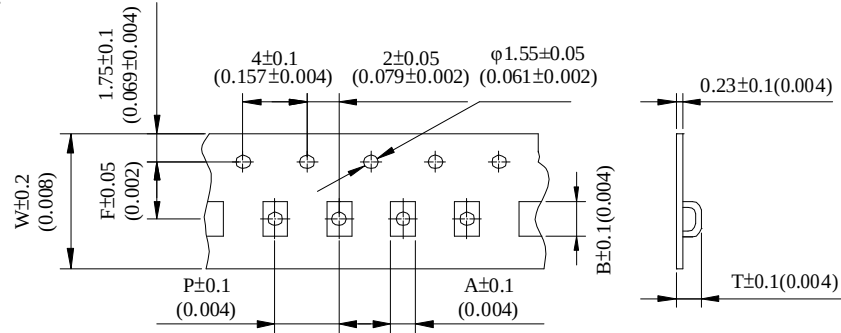
REF :

PAGE: 5

PROD. NAME	MULTILAYER CHIP INDUCTOR	ABC'S DWG NO.	MS3261□□□□L□-□□□
		ABC'S ITEM NO.	

(4) TYPE DIMENSIONS

Fig 2.



Unit:m/m

Type	A	B	F	P	T	W	Fig
MS3261	1.88	3.50	3.50	4.0	1.27	8.0	2

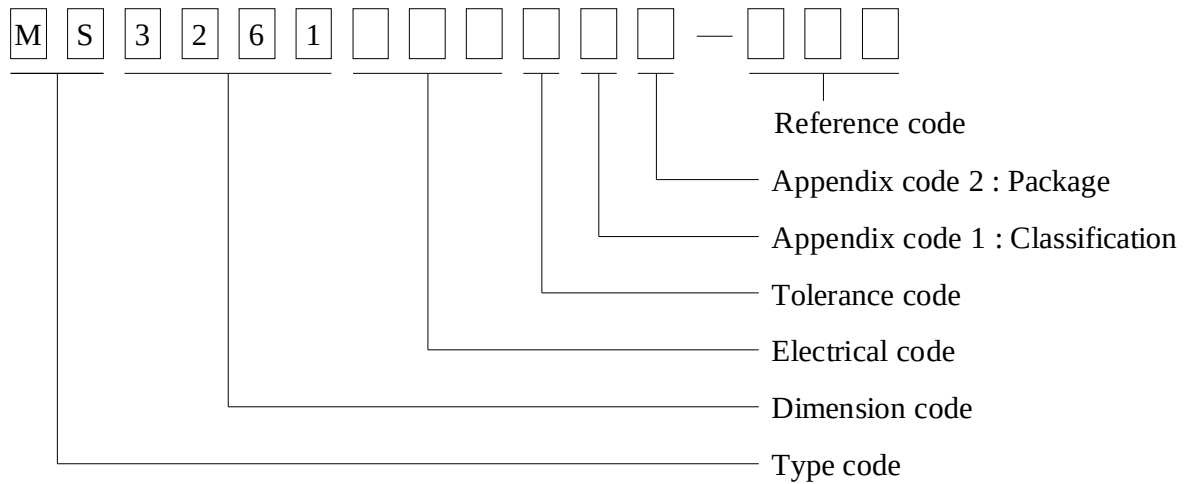
SPECIFICATION FOR APPROVAL

REF :

PAGE: 6

PROD. NAME	MULTILAYER CHIP INDUCTOR	ABC'S DWG NO.	MS3261□□□□L□-□□□
		ABC'S ITEM NO.	

VIII . DWGING NUMBER EXPRESSION :



Appendix code 1 : Product Classification

L : Lead Free Standard products comply with RoHS' requirements

1 ~ 9 : Lead Free Special products comply with RoHS' requirements

Appendix code 2 : Package Information

Code	Inner package	Inner package Q'TY	Remark
A	T.B.D.	T.B.D.	
B	T / R (Reel package)	3000 pcs	

AR-001A